

Description

The FQD7P06 uses advanced trench

technology to provide excellent $R_{\text{DS}(\text{ON})}$, low gate

charge and operation with gate voltages as low

as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-10 A

 $R_{DS(ON)} < 140 m\Omega @ V_{GS} = 10V$

Application

Brushless motor

Load switch

Uninterruptible power supply

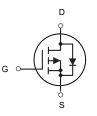
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
FQD7P06	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage ±20		V
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ -10V ¹	Continuous Drain Current, V _{GS} @ -10V ¹ -10	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	Continuous Drain Current, V _{GS} @ -10V ¹ -8.3	
Ідм	Pulsed Drain Current ²	Pulsed Drain Current ² -26	
EAS	Single Pulse Avalanche Energy ³ 29.8		mJ
las	Avalanche Current -24.4		А
P _D @T _C =25°C	Total Power Dissipation ⁴	Total Power Dissipation ⁴ 31.3	
Тѕтс	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range -55 to 150		°C
Reja	Thermal Resistance Junction-Ambient ¹	hermal Resistance Junction-Ambient ¹ 62 °C	
Rejc	Thermal Resistance Junction-Case ¹	4.0 °C/W	





P-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
∆BV _{DSS} /∆T	BV _{DSS} Temperature Coefficient	Reference to $25^{\circ}C$, I _D =-1mA		-0.049		V/°C	
-	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-8A		125	140		
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-6A	168		210	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage		-1.0		-2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , ID2500A		5.42		mV/°C	
I		V_{DS} =-48V , V_{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =150°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-5A		5.8		S	
Qg	Total Gate Charge (-4.5V)			5.85			
Q_gs	Gate-Source Charge	V_{DS} =-20V , V_{GS} =-4.5V , I_{D} =-5A		2.9		nC	
Q_{gd}	Gate-Drain Charge			1.8			
T _{d(on)}	Turn-On Delay Time			10			
Tr	Rise Time	V_{DD} =-12V , V_{GS} =-10V , R_G =3.3 Ω ,		17		ns	
$T_{d(off)}$	Turn-Off Delay Time	I _D =-5A		22			
T _f	Fall Time			21			
Ciss	Input Capacitance			715			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , F=1MHz		51		pF	
C _{rss}	Reverse Transfer Capacitance			34			
Is	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			-9.5	А	
I _{SM}	Pulsed Source Current ^{2,5}	vg-vD-0v, roice Current			-24	Α	
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1.2	V	
t _{rr}	Reverse Recovery Time			10.2		nS	
Qrr	Reverse Recovery Charge	I⊧=-8A , dl/dt=100A/µs , Tյ=25°C		5.4		nC	

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating. The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH,I_{AS}=-15A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

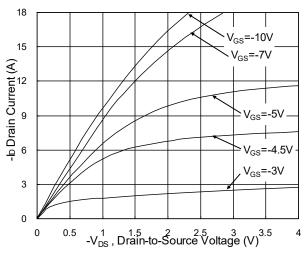


Fig.1 Typical Output Characteristics

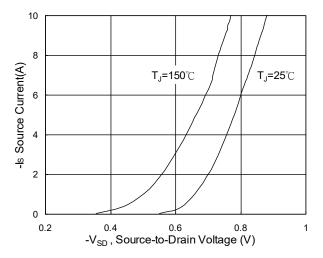
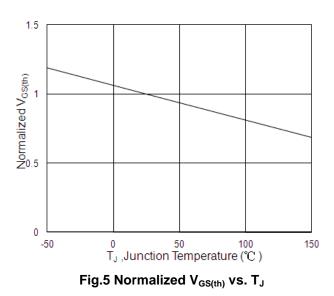


Fig.3 Forward Characteristics Of Reverse



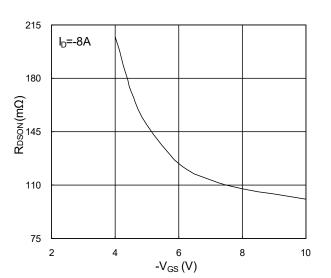


Fig.2 On-Resistance vs. G-S Voltage

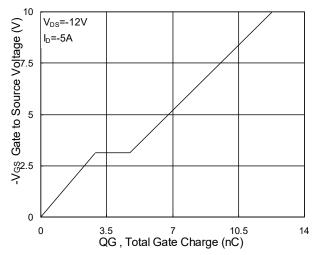


Fig.4 Gate-Charge Characteristics

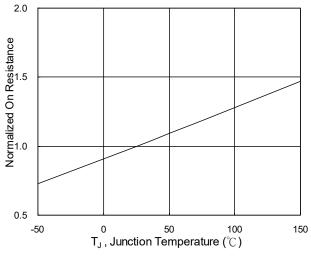
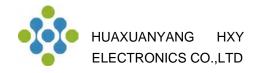
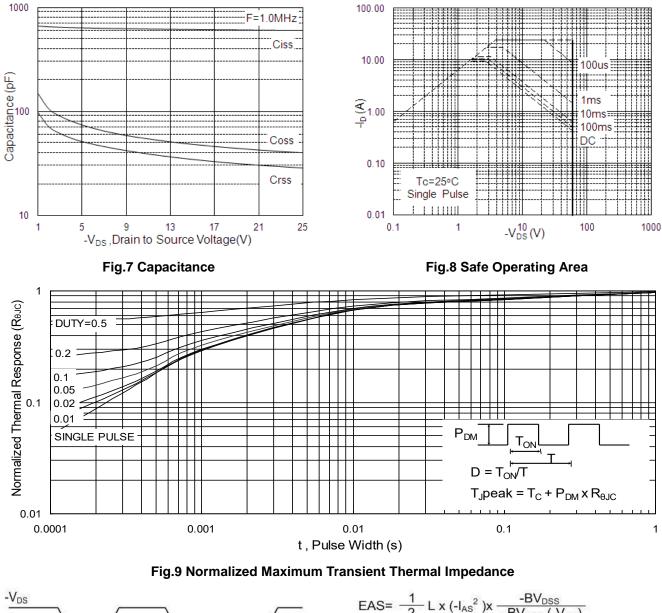


Fig.6 Normalized R_{DSON} vs. T_J





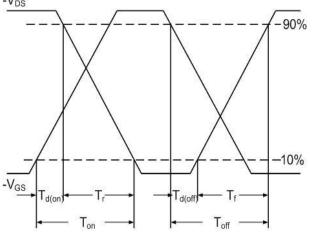


Fig.10 Switching Time Waveform

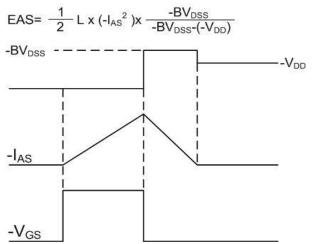
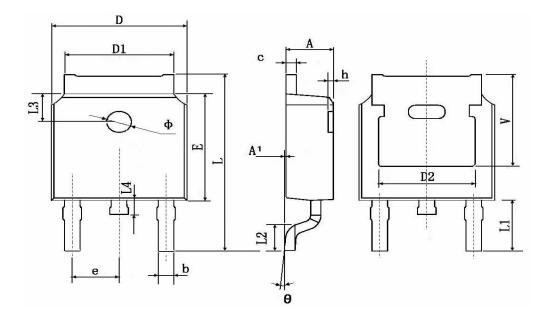


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0 °	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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